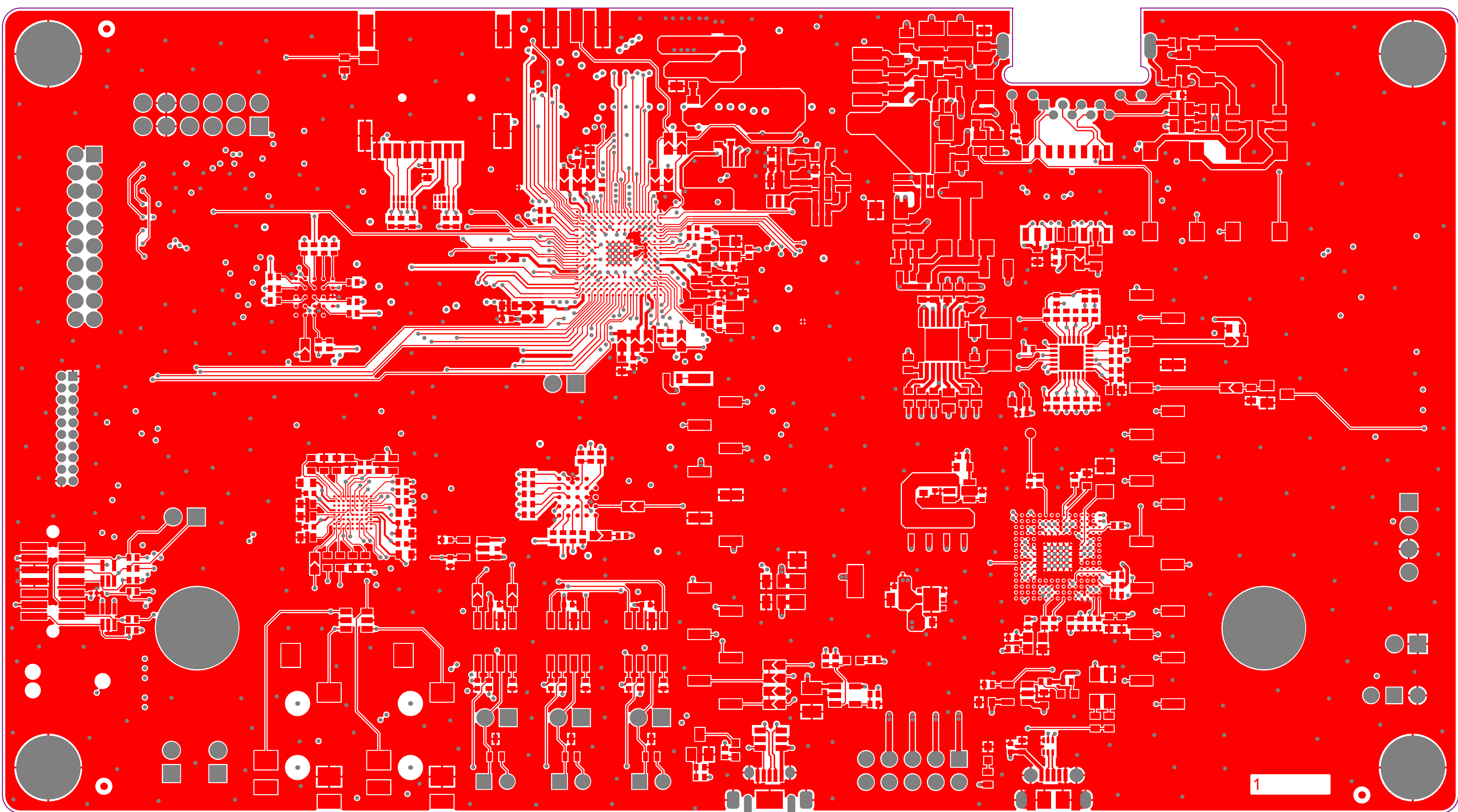


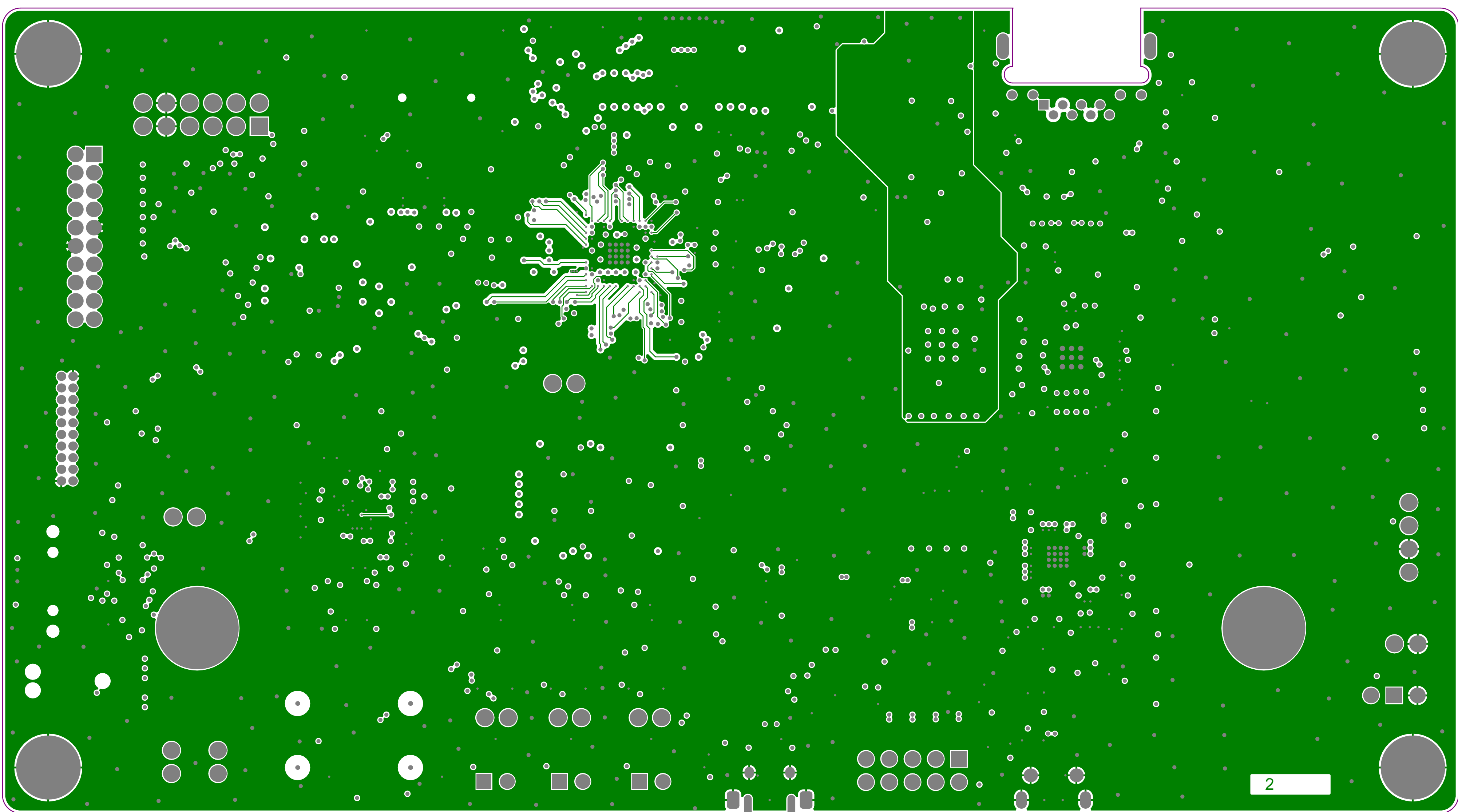
Top Solder

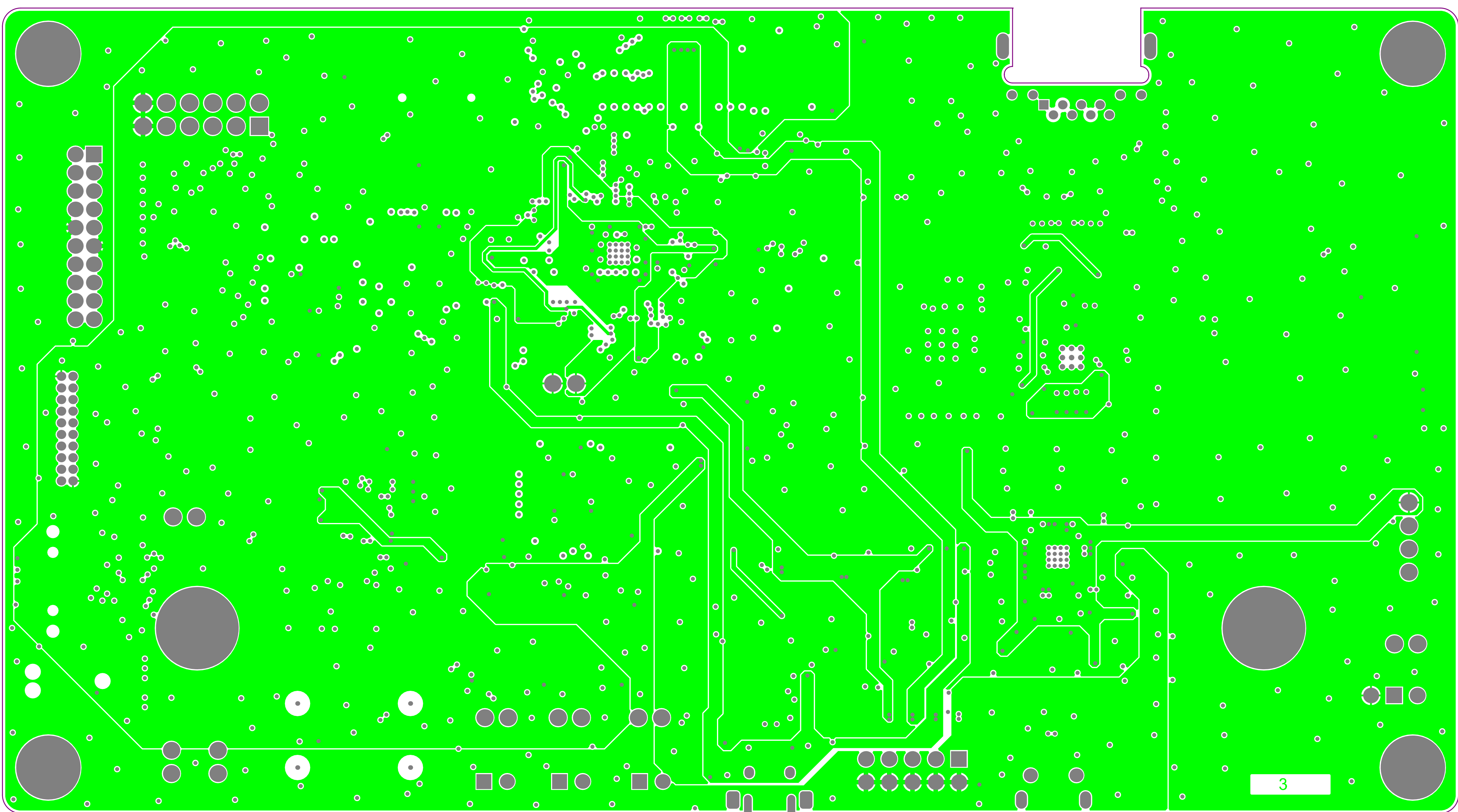
.GTS



Top Layer

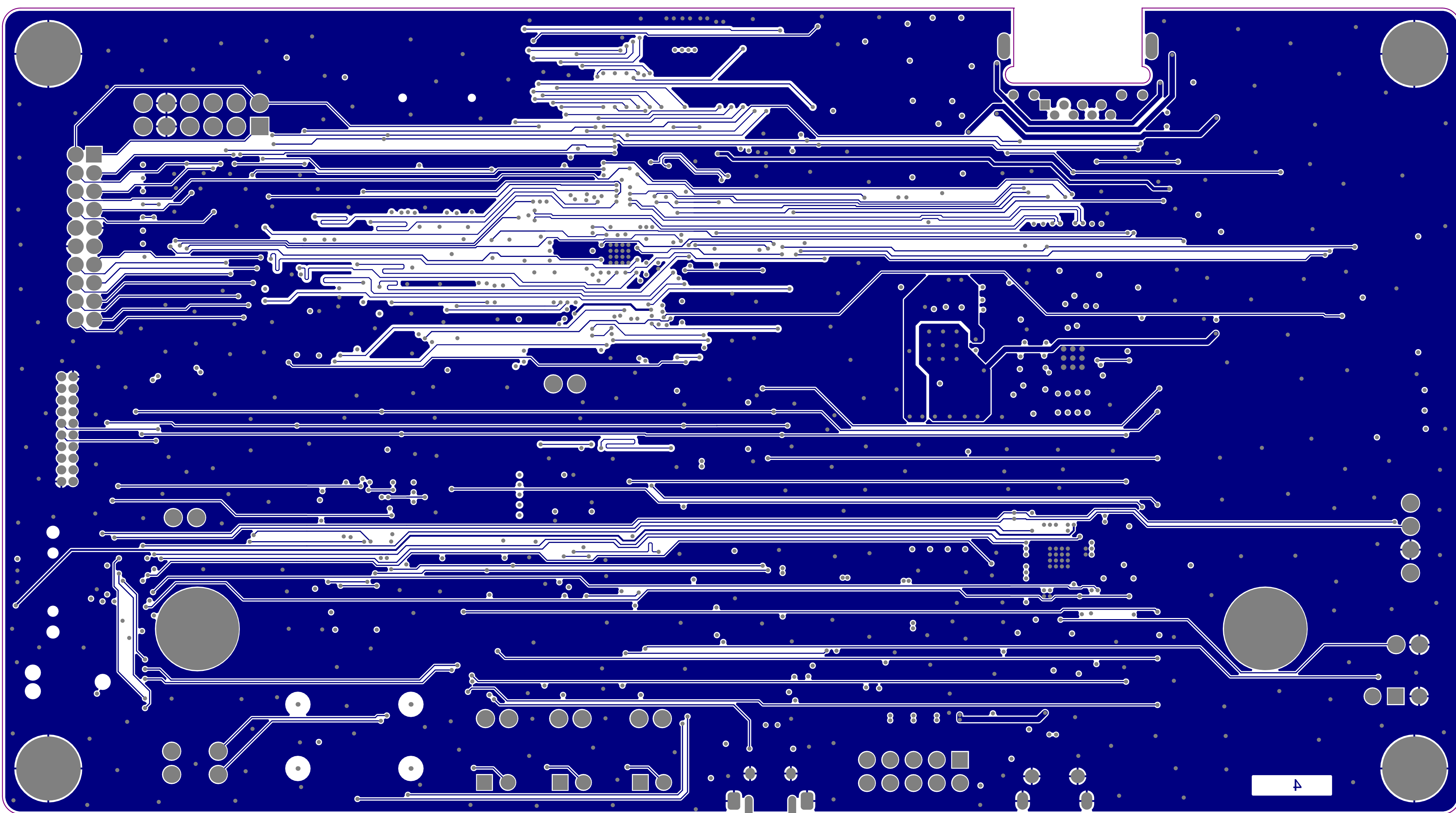
.GTL

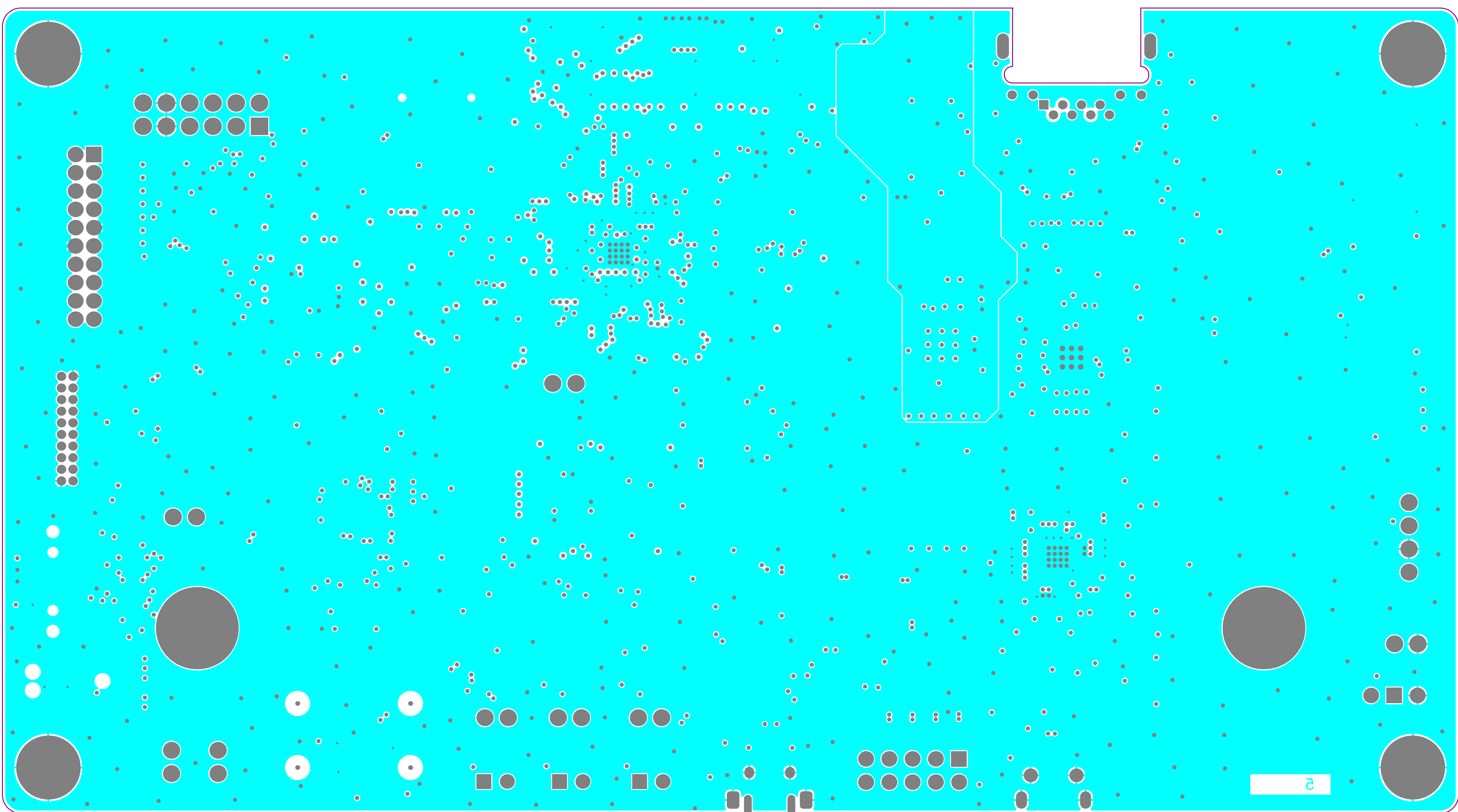


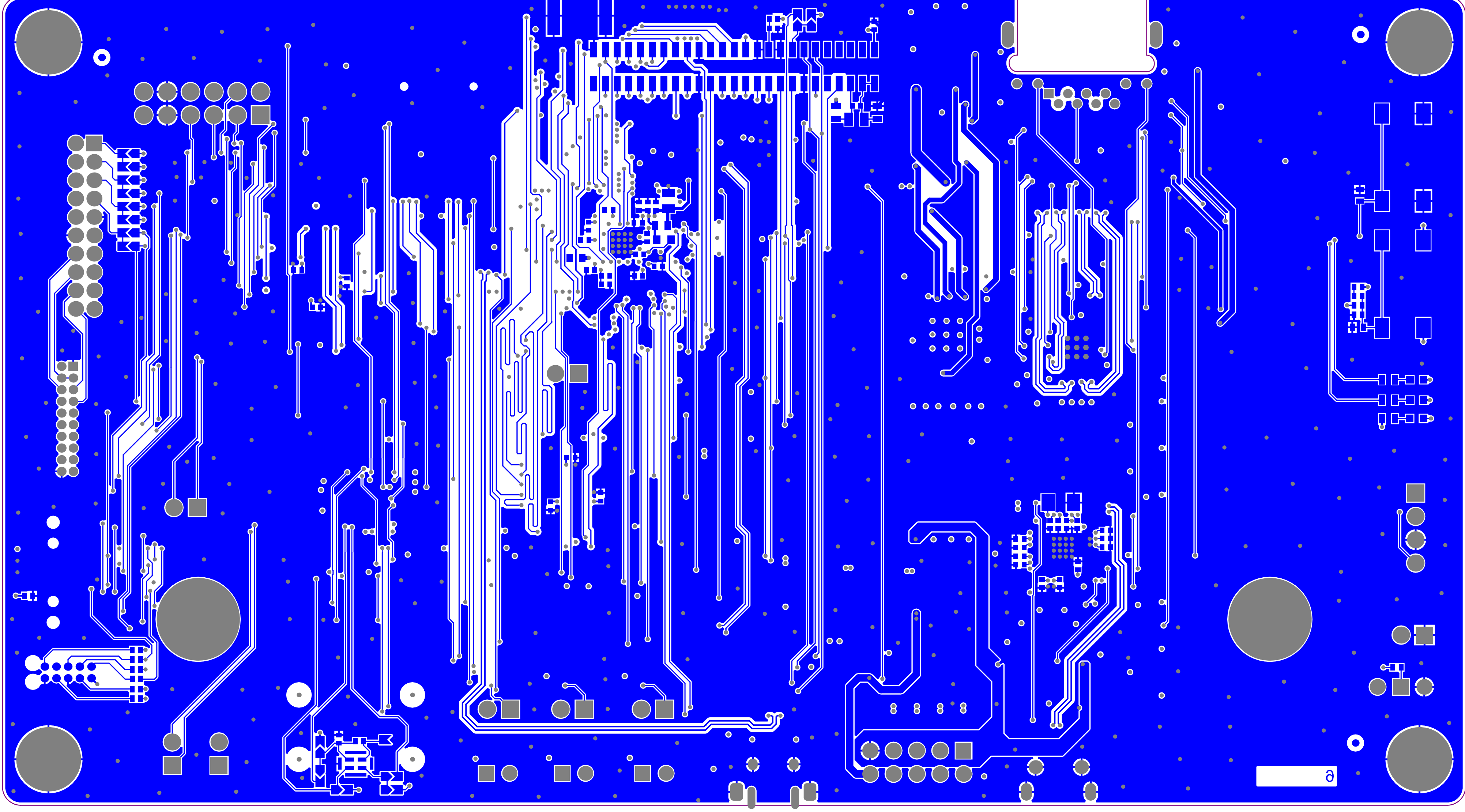


Signal Layer 2

.G2

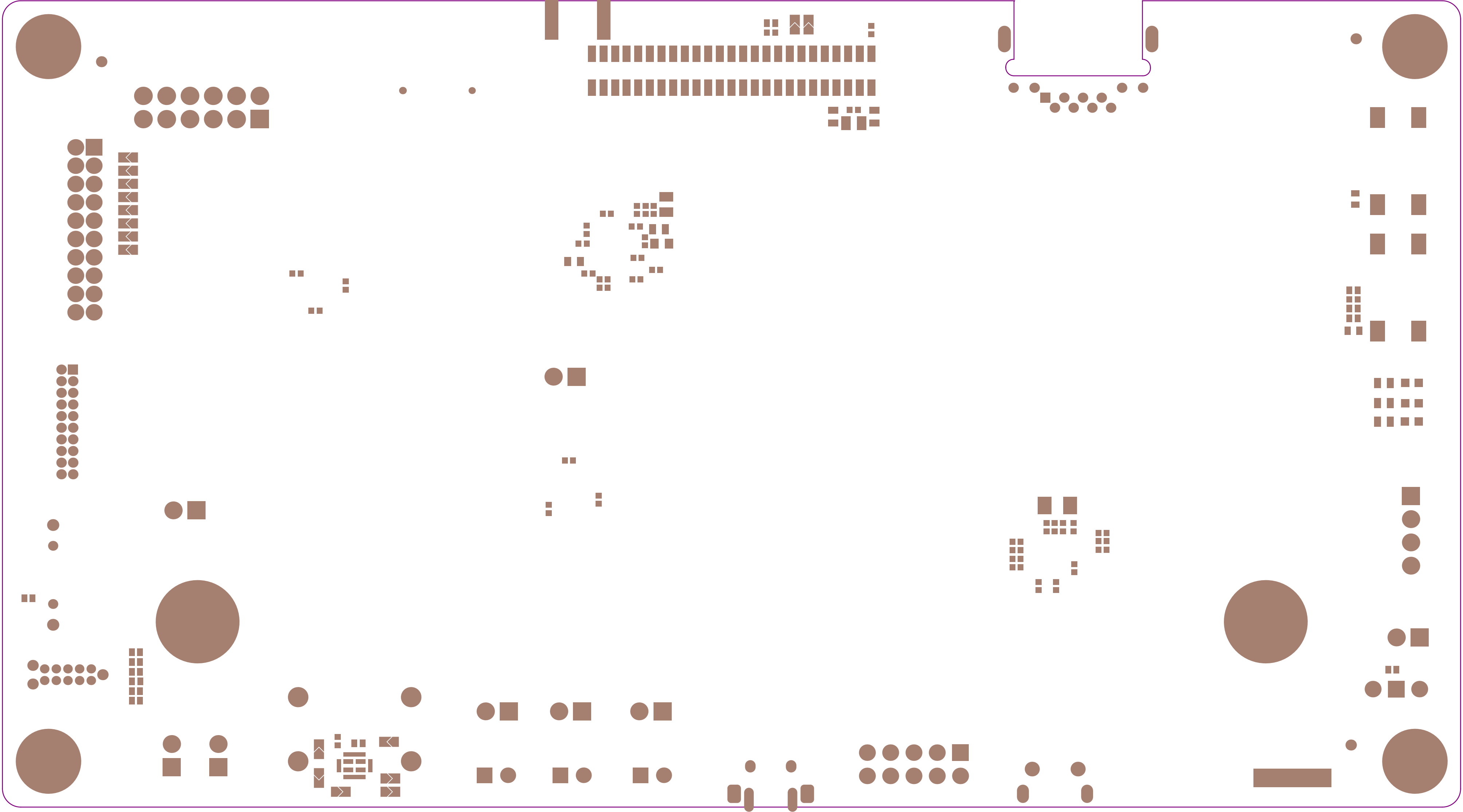




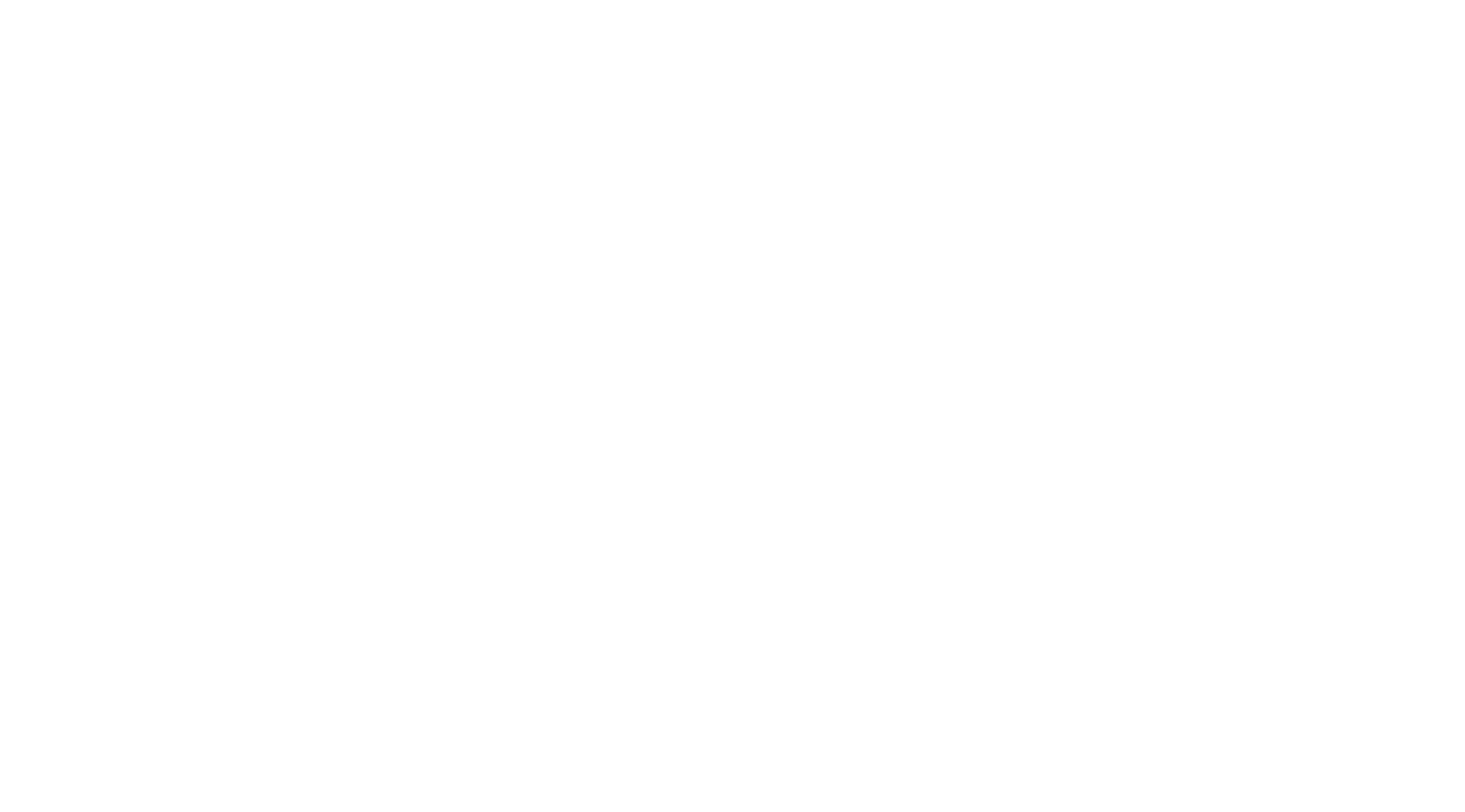


Bottom Layer

GBL



Bottom Solder
.GB2





PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☐ NO

☐ TG-170

☒ TG-150

☐ TG-140

☐ WHITE

☒ BLUE

☐ BLACK

☐ Blue ink PANTONE 2955

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ GOLDEN FINGER

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.12mm
GAPS : 0.12mm

MCU / BGA
TRACKS : 0.09mm
GAPS : 0.08mm

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| 1 | Top Overlay | | | | |
| 2 | Top Solder | Solder Resist | 0,015mm | 3,5 | |
| 3 | Top Layer | Copper | 0,042mm | | |
| 4 | Dielectric1 | FR-4 | 0,099mm | 4,2 | |
| 5 | Signal Layer 1 | Copper | 0,035mm | | |
| 6 | Dielectric 2 | | 0,102mm | 4,2 | |
| 7 | Signal Layer 2 | Copper | 0,035mm | | |
| 8 | Dielectric 3 | FR-4 | 0,946mm | 4,2 | |
| 9 | Signal Layer 3 | Copper | 0,035mm | | |
| 10 | Dielectric 4 | | 0,102mm | 4,2 | |
| 11 | Signal Layer 4 | Copper | 0,035mm | | |
| 12 | Dielectric 5 | FR-4 | 0,099mm | 4,2 | |
| 13 | Bottom Layer | Copper | 0,042mm | | |
| 14 | Bottom Solder | Solder Resist | 0,015mm | 3,5 | |
| 15 | Bottom Overlay | | | | |

| Symbol | Count | Hole Size | Plated | Hole Type | Drill Layer Pair | Via/Pad | Hole Length | Routed Path Length |
|--------|------------|--------------------|--------|-----------|--------------------------|---------|-------------------|--------------------|
| ☆ | 1099 | 0,20mm (7,87mil) | PTH | Round | Top Layer - Bottom Layer | Via | - | - |
| ○ | 9 | 0,30mm (11,81mil) | PTH | Round | Top Layer - Bottom Layer | Via | - | - |
| ◇ | 4 | 0,60mm (23,62mil) | PTH | Slot | Top Layer - Bottom Layer | Pad | 1,30mm (51,18mil) | 0,70mm (27,56mil) |
| ⌒ | 2 | 0,65mm (25,59mil) | PTH | Slot | Top Layer - Bottom Layer | Pad | 0,85mm (33,47mil) | 0,20mm (7,88mil) |
| ○ | 1 | 0,65mm (25,59mil) | NPTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| ⊖ | 1 | 0,70mm (27,56mil) | NPTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| ✱ | 32 | 0,70mm (27,56mil) | PTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| □ | 2 | 0,70mm (27,56mil) | PTH | Slot | Top Layer - Bottom Layer | Pad | 2,20mm (86,61mil) | 1,50mm (59,06mil) |
| ◎ | 2 | 0,85mm (33,47mil) | NPTH | Slot | Top Layer - Bottom Layer | Pad | 2,42mm (95,47mil) | 1,57mm (62,01mil) |
| ▣ | 25 | 0,90mm (35,43mil) | PTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| ✱ | 2 | 0,97mm (38,19mil) | NPTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| ▽ | 26 | 1,00mm (39,37mil) | PTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| F | 3 | 1,10mm (43,31mil) | NPTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| M | 22 | 1,10mm (43,31mil) | PTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| L | 2 | 1,19mm (46,85mil) | NPTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| B | 4 | 2,00mm (78,74mil) | NPTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| E | 4 | 3,50mm (137,80mil) | PTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| Q | 2 | 4,50mm (177,17mil) | PTH | Round | Top Layer - Bottom Layer | Pad | - | - |
| | 1242 Total | | | | | | | |

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Drawing

.DRL